

International **IR** Rectifier

- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Lead-Free

Description

Advanced HEXFET® Power MOSFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The D²Pak is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²Pak is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0W in a typical surface mount application.

The through-hole version (IRF540NL) is available for low-profile applications.

Absolute Maximum Ratings

	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V ⑦	33	A
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V ⑦	23	
I _{DM}	Pulsed Drain Current ①⑦	110	
P _D @T _C = 25°C	Power Dissipation	130	W
	Linear Derating Factor	0.87	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
I _{AR}	Avalanche Current①	16	A
E _{AR}	Repetitive Avalanche Energy①	13	mJ
dv/dt	Peak Diode Recovery dv/dt ③⑦	7.0	V/ns
T _J T _{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Thermal Resistance

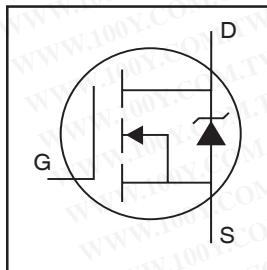
	Parameter	Typ.	Max.	Units
R _{θJC}	Junction-to-Case	—	1.15	°C/W
R _{θJA}	Junction-to-Ambient (PCB mount)**	—	40	

PD - 95130

IRF540NSPbF

IRF540NLPbF

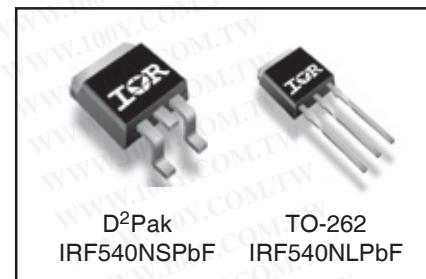
HEXFET® Power MOSFET



V_{DSS} = 100V

R_{DS(on)} = 44mΩ

I_D = 33A



D²Pak TO-262
IRF540NSPbF IRF540NLPbF

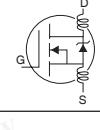
勝特力材料 886-3-5753170

胜特力电子(上海) 86-21-34970699

胜特力电子(深圳) 86-755-83298787

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}/\Delta T_J}$	Breakdown Voltage Temp. Coefficient	—	0.12	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1\text{mA}$ ⑦
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	44	$\text{m}\Omega$	$V_{\text{GS}} = 10\text{V}$, $I_D = 16\text{A}$ ④
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$
g_{fs}	Forward Transconductance	21	—	—	S	$V_{\text{DS}} = 50\text{V}$, $I_D = 16\text{A}$ ④⑦
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{\text{DS}} = 100\text{V}$, $V_{\text{GS}} = 0\text{V}$
		—	—	250		$V_{\text{DS}} = 80\text{V}$, $V_{\text{GS}} = 0\text{V}$, $T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{\text{GS}} = 20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}} = -20\text{V}$
Q_g	Total Gate Charge	—	—	71	nC	$I_D = 16\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	14		$V_{\text{DS}} = 80\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	21		$V_{\text{GS}} = 10\text{V}$, See Fig. 6 and 13 ④⑦
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	11	—	ns	$V_{\text{DD}} = 50\text{V}$
t_r	Rise Time	—	35	—		$I_D = 16\text{A}$
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	39	—		$R_G = 5.1\Omega$
t_f	Fall Time	—	35	—		$V_{\text{GS}} = 10\text{V}$, See Fig. 10 ④⑦
L_D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	7.5	—		
C_{iss}	Input Capacitance	—	1960	—	pF	$V_{\text{GS}} = 0\text{V}$
C_{oss}	Output Capacitance	—	250	—		$V_{\text{DS}} = 25\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	40	—		$f = 1.0\text{MHz}$, See Fig. 5 ⑦
E_{AS}	Single Pulse Avalanche Energy ②⑦	—	700③	185⑥	mJ	$I_{\text{AS}} = 16\text{A}$, $L = 1.5\text{mH}$

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	33	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode)①	—	—			
V_{SD}	Diode Forward Voltage	—	—	1.2	V	$T_J = 25^\circ\text{C}$, $I_S = 16\text{A}$, $V_{\text{GS}} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	115	170	ns	$T_J = 25^\circ\text{C}$, $I_F = 16\text{A}$
Q_{rr}	Reverse Recovery Charge	—	505	760	nC	$dI/dt = 100\text{A}/\mu\text{s}$ ④⑦
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② Starting $T_J = 25^\circ\text{C}$, $L = 1.5\text{mH}$
 $R_G = 25\Omega$, $I_{\text{AS}} = 16\text{A}$. (See Figure 12)
- ③ $I_{\text{SD}} \leq 16\text{A}$, $di/dt \leq 340\text{A}/\mu\text{s}$, $V_{\text{DD}} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$
- ④ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.

⑤ This is a typical value at device destruction and represents operation outside rated limits.

⑥ This is a calculated value limited to $T_J = 175^\circ\text{C}$.

⑦ Uses IRF540N data and test conditions.

**When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994

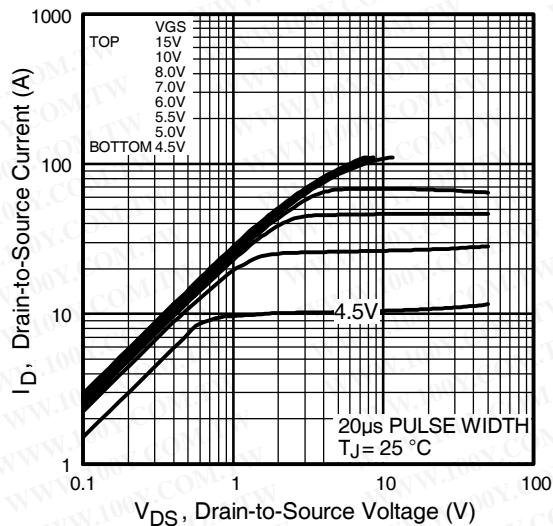


Fig 1. Typical Output Characteristics

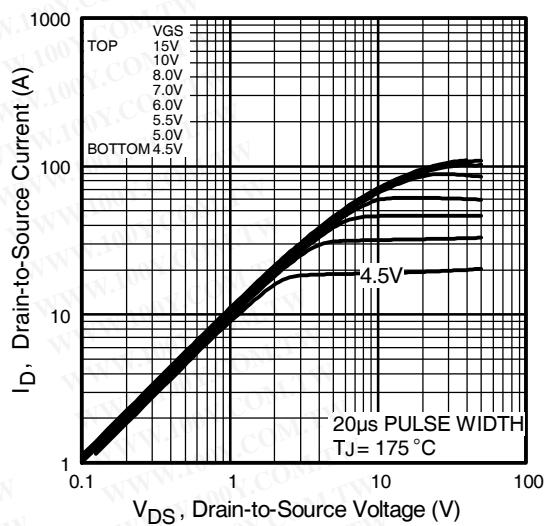


Fig 2. Typical Output Characteristics

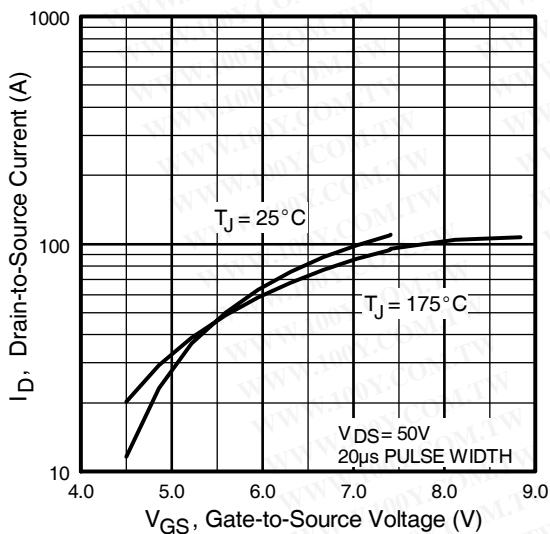


Fig 3. Typical Transfer Characteristics

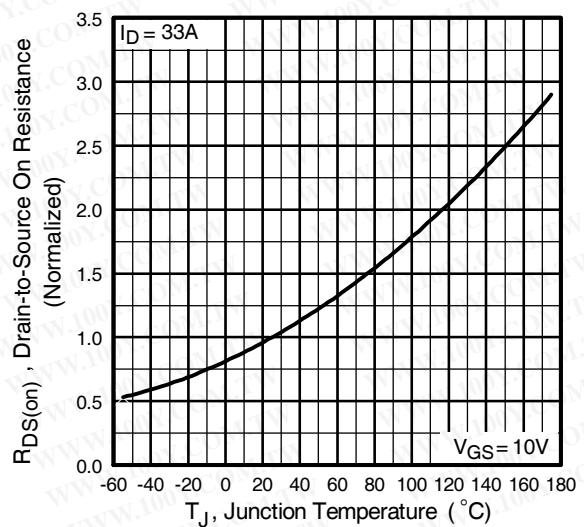


Fig 4. Normalized On-Resistance
Vs. Temperature

IRF540NS/LPbF

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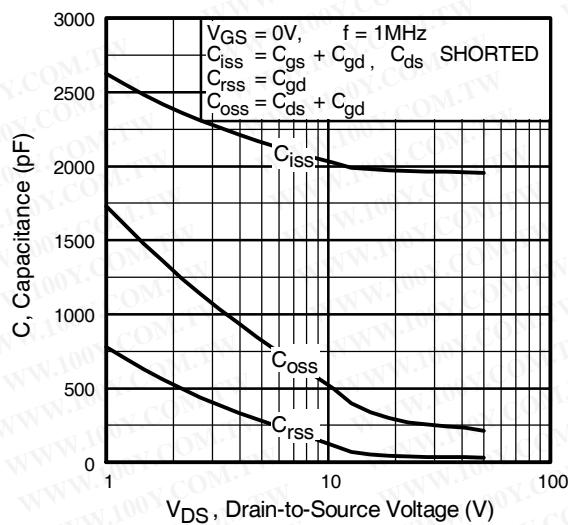


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

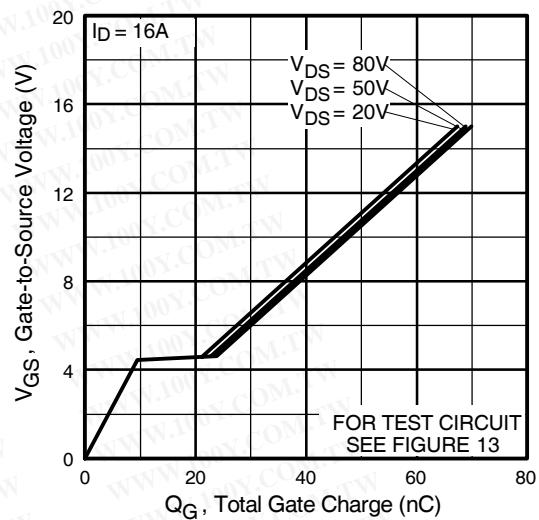


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

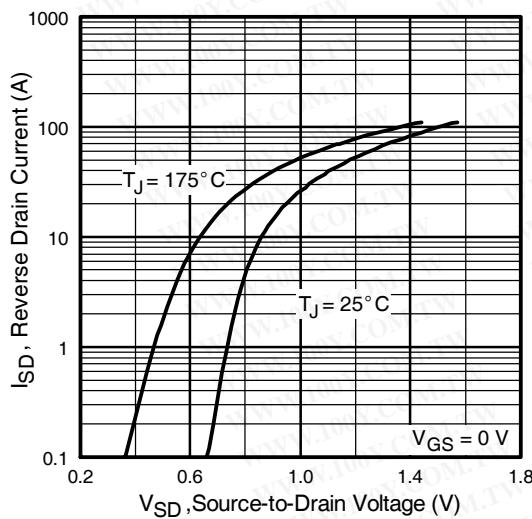


Fig 7. Typical Source-Drain Diode
Forward Voltage

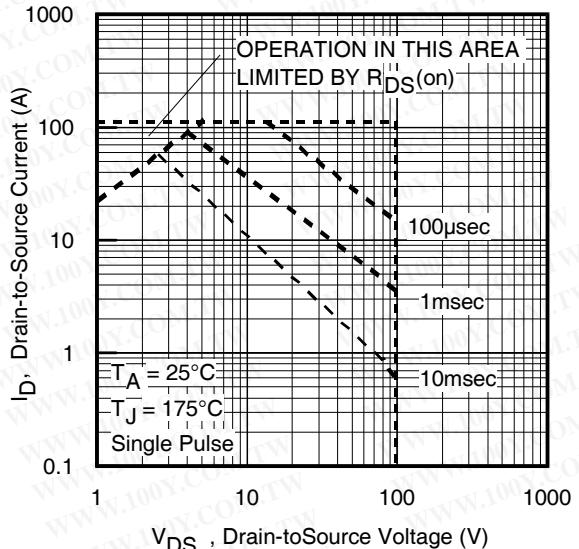


Fig 8. Maximum Safe Operating Area

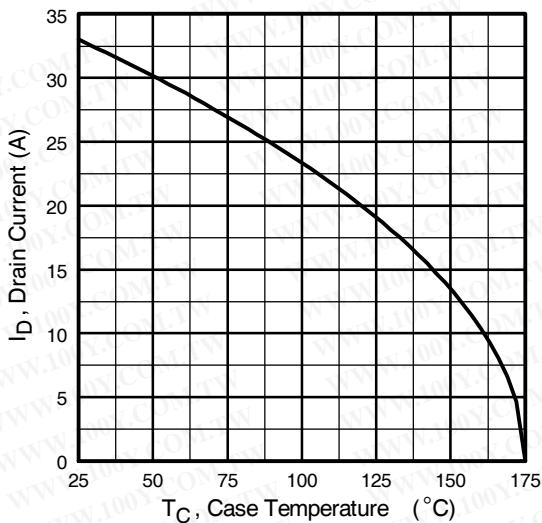


Fig 9. Maximum Drain Current Vs.
Case Temperature

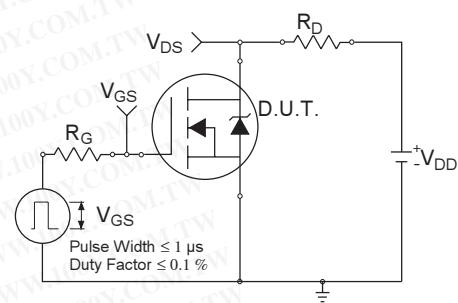


Fig 10a. Switching Time Test Circuit

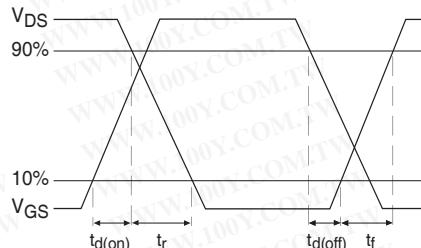


Fig 10b. Switching Time Waveforms

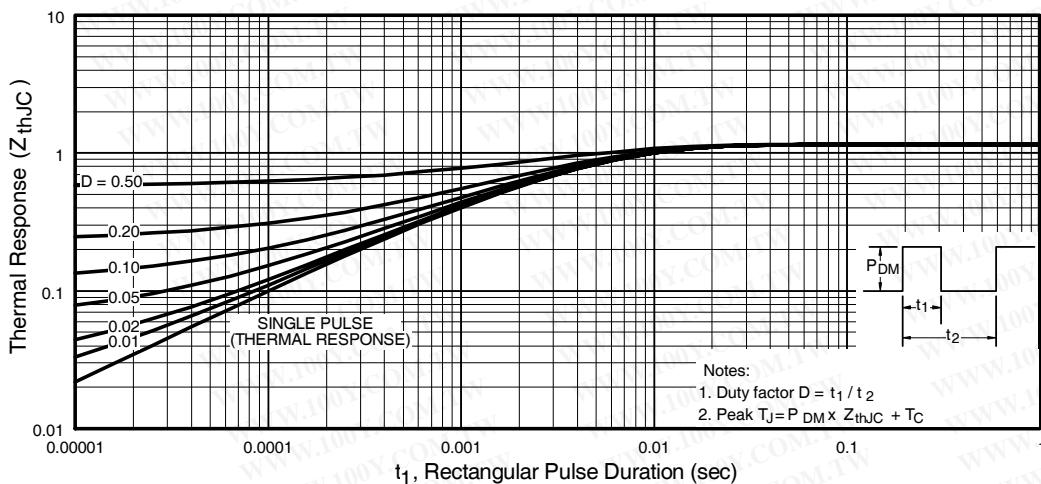


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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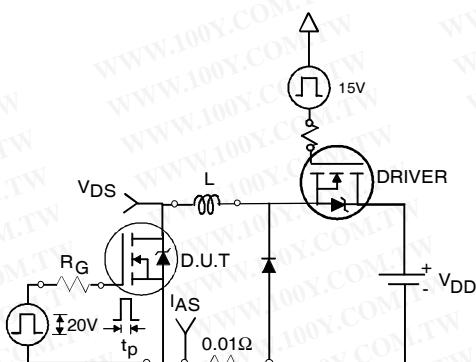


Fig 12a. Unclamped Inductive Test Circuit

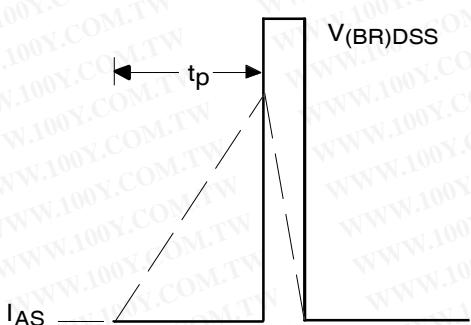


Fig 12b. Unclamped Inductive Waveforms

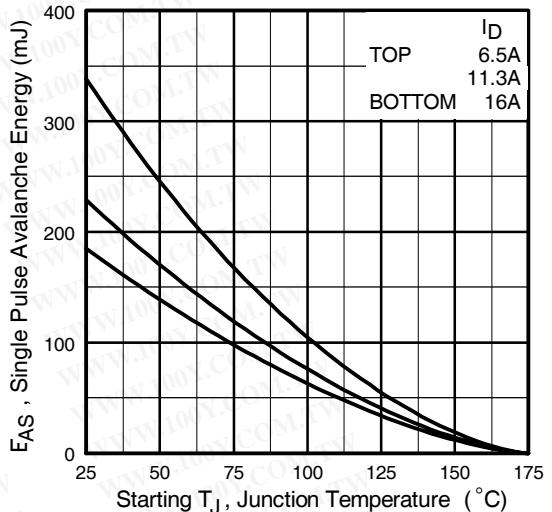


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

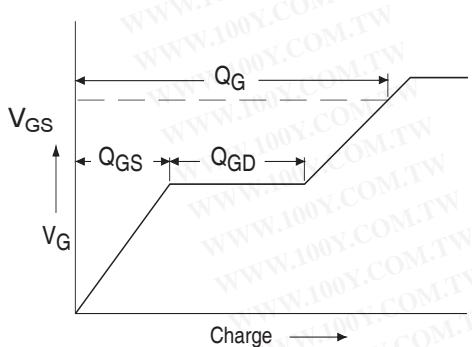


Fig 13a. Basic Gate Charge Waveform

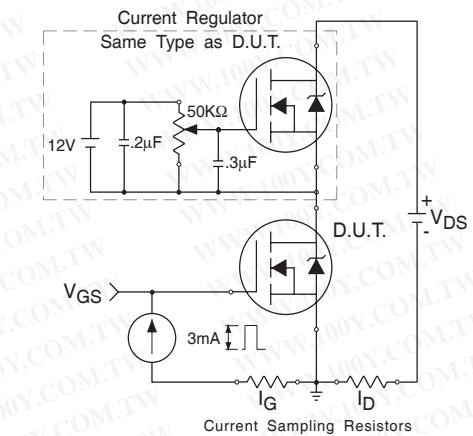
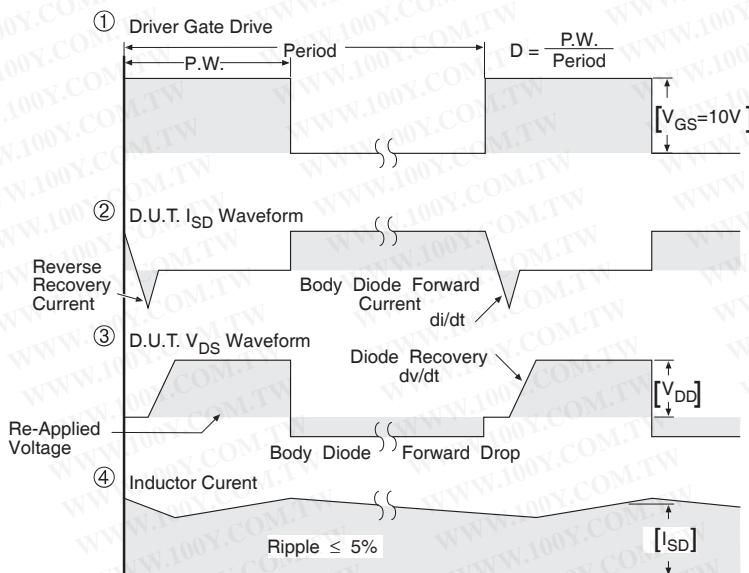
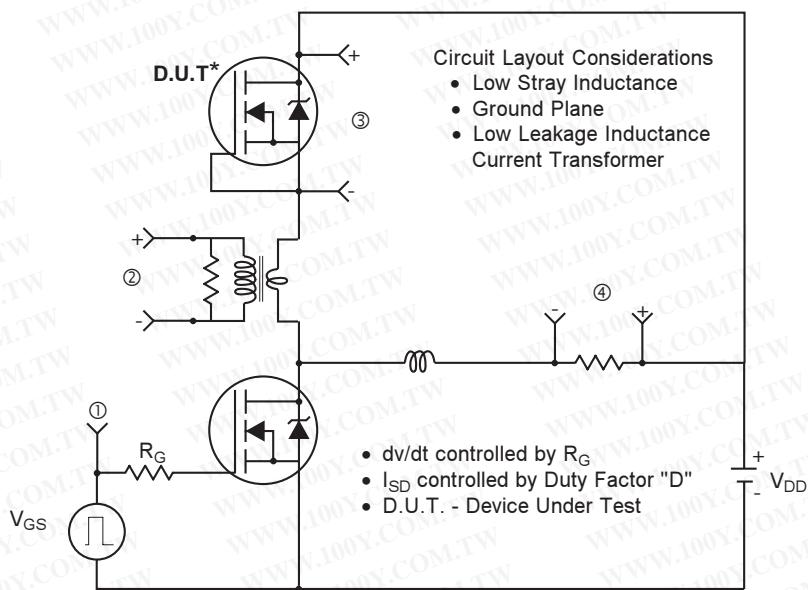


Fig 13b. Gate Charge Test Circuit

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Peak Diode Recovery dv/dt Test Circuit



*** $V_{GS} = 5.0V$ for Logic Level and 3V Drive Devices

Fig 14. For N-channel HEXFET® power MOSFETs

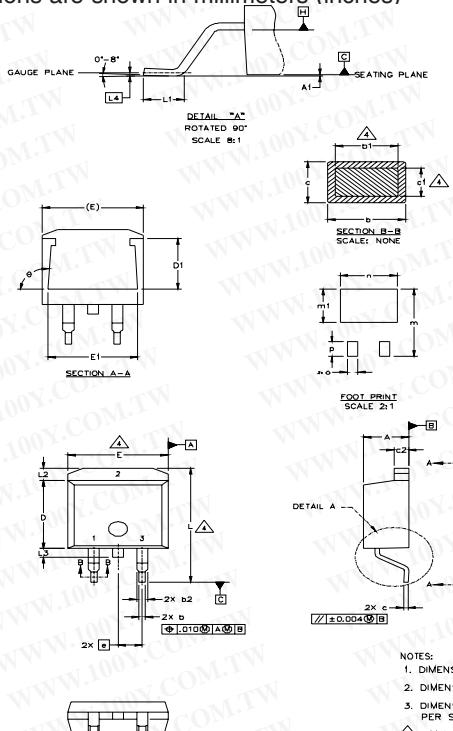
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D²Pak Package Outline

Dimensions are shown in millimeters (inches)



SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	4.06	4.83	.160	.190		
A1			.0127	.005		
b	0.51	0.99	.020	.039		
b1	0.51	0.89	.020	.035	4	
b2	1.14	1.40	.045	.055		
c	0.43	0.63	.017	.025		
c1	0.38	0.74	.015	.029	4	
c2	1.14	1.40	.045	.055		
D	8.51	9.85	.335	.380	3	
D1	5.33		.210			
E	9.65	10.67	.380	.420		
E1	6.22		.245		3	
e	2.54	BSC	.100	BSC		
L	14.61	15.88	.575	.625		
L1	1.78	2.79	.070	.110		
L2			1.65	.065		
L3	1.27	1.78	.050	.070		
L4	0.25	BSC	.010	BSC		
m	17.78		.700			
m1	8.89		.350			
n	11.43		.450			
o	2.08		.082			
p	3.81		.150			
θ	90°	93°	90°	93°		

LEAD ASSIGNMENTS

HEXFET	IGBT _s , CoPACK	DIODES
1.- GATE 2.- DRAIN 3.- SOURCE	1.- GATE 2.- COLLECTOR 3.- Emitter	1.- ANODE * 2.- CATHODE 3.- ANODE

* PART DEPENDENT.

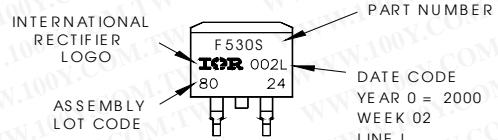
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.05"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
5. CONTROLLING DIMENSION: INCH.

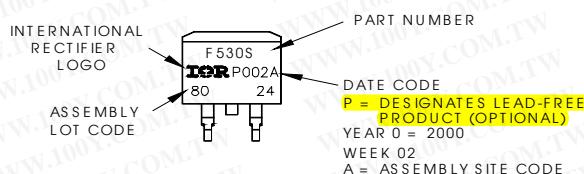
D²Pak Part Marking Information (Lead-Free)

EXAMPLE: THIS IS AN IRF530S WITH
 LOT CODE 8024
 ASSEMBLED ON WW 02, 2000
 IN THE ASSEMBLY LINE "L"

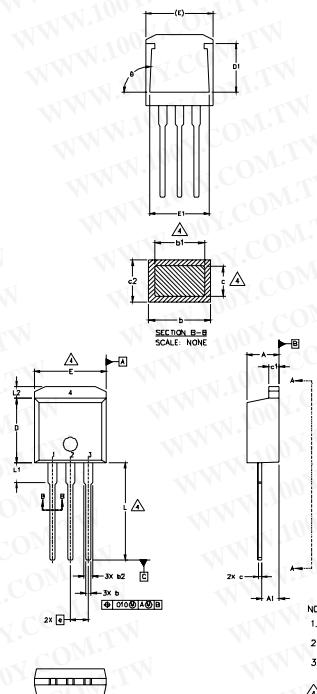
Note: "P" in assembly line
 position indicates "Lead-Free"



OR



TO-262 Package Outline



SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	4.06	4.83	.160	.190		
A1	2.03	2.92	.080	.115		
b	0.51	0.99	.020	.039		
b1	0.51	0.89	.020	.035	4	
b2	1.14	1.40	.045	.055		
c	0.38	0.63	.015	.025	4	
c1	1.14	1.40	.045	.055		
c2	0.43	.063	.017	.029		
D	8.51	9.65	.335	.380	3	
D1	5.33		.210			
E	9.65	10.67	.380	.420	3	
E1	6.22		.245			
e	2.54	BSC	.100	BSC		
L	13.46	14.09	.530	.555		
L1	3.56	3.71	.140	.146		
L2		1.65		.065		

LEAD ASSIGNMENTS

IGBT

- | | |
|--------|--------------|
| HEXFET | 1- GATE |
| | 2- COLLECTOR |
| | 3- SOURCE |
| | 4- DRAIN |

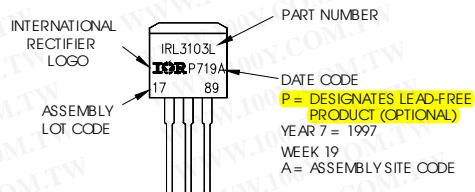
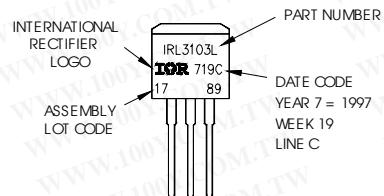
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 △ DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
 5. CONTROLLING DIMENSION: INCH.

TO-262 Part Marking Information

EXAMPLE: THIS IS AN IRL3103L
LOT CODE 1789
ASSEMBLED ON WV 19, 1997
IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position indicates "Lead-Free"

OR

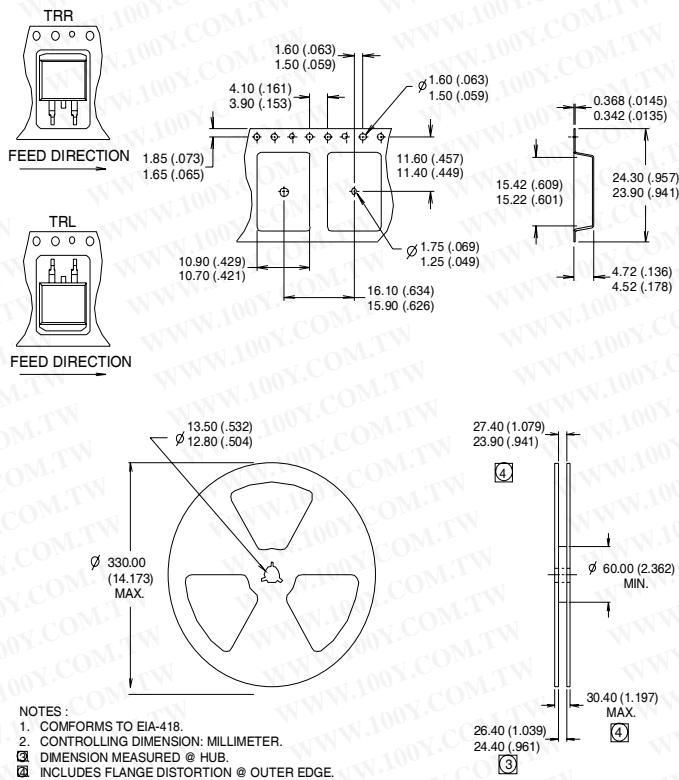


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D²Pak Tape & Reel Infomation

Dimensions are shown in millimeters (inches)



Data and specifications subject to change without notice.
This product has been designed and qualified for the industrial market.
Qualification Standards can be found on IR's Web site.

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